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REMARKS/ARGUMENTS

Claims 1-3 are pending in this application. By this Amendment, Applicants AMEND the Specification, the Title of the Invention, and claims 1-3.

The Examiner objected to the Specification and the Title of the Invention for allegedly containing minor informalities. Applicants have amended the Specification and the Title of the Invention to correct the minor informalities noted by the Examiner. Accordingly, Applicants respectfully request reconsideration and withdrawal of the objections to the Specification and the Title of the Invention.

The Examiner objected to claims 1-3 for allegedly containing minor informalities. Applicants have amended claims 1-3 to correct the minor informalities noted by the Examiner. Accordingly, Applicants respectfully request reconsideration and withdrawal of the objection to claim .

Claims 2 and 3 were rejected under 35 U.S.C. §112, second paragraph as allegedly being indefinite. Claims 2 and 3 have been amended to correct the informalities noted by the Examiner. Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claims 2 and 3 under 35 U.S.C. § 112, second paragraph.

Claims 1-3 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Brebels et al. (U.S. 5,675,295) in view of Kornrumpf et al. (U.S. 5,355,102), further in view of Carey et al. (U.S. 5,219,787), further in view of Ohya et al. (U.S. 5,686,172), and further in view of at least one of: Trinh et al. (U.S. 5,132,648), Peterson (U.S. 5,574,415), and/or Kroger (U.S. 4,490,733). Applicants respectfully traverse the rejection of claims 1-3.

Claim 1 has been amended to recite:

"A method of producing a thin film circuit board used as a milli-wave or micro-wave module, the method comprising steps of:

cleaning a substrate comprising dielectric ceramic, and having a thickness of 0.05 mm to 2 mm and a flexural strength of 500 kgf/cm² to 4000 kgf/cm²;

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forming a conductor film in a predetermined pattern on the substrate, said conductor film including at least one selected from Cu, Au, Ag, Al, Ni, Ti, Cr, Ni-Cr, Nb, and V;

forming an insulating film on the substrate to cover the conductor film, said insulating film comprising at least one organic resin selected from polyimide, epoxy resins, benzocyclobutene resins, acrylic resins, and cyclic olefin resins, and having a thickness of 20 μm or greater, an area of 5 cm^2 or less per pattern, and a stress of 15 MPa to 60 MPa;

patterning the insulating film; and

repeating the insulating film forming step and the insulating film patterning step more than once." (emphasis added)

Applicants' claim 1 recites the steps of "forming an insulating film on the substrate to cover the conductor film" and "repeating the insulating film forming step and the insulating film patterning step more than once." With the improved features of claim 1, Applicants have been able to provide an improved method of producing a thin film circuit board even when an insulating film comprising an organic resin is thickened (see, for example, the paragraph bridging pages 3 and 4 of the Specification).

The Examiner has relied upon lines 22-44 of column 19 of Brebels et al. to allegedly teach the step of "repeating the insulating film forming step and the insulating film patterning step more than once" as recited in Applicants' claim 1.

First, this portion of Brebels et al. which the Examiner relied upon to allegedly teach the step of "repeating the insulating film forming step and the insulating film patterning step more than once" is directed to the third embodiment, whereas lines 20-35 of column 8 of Brebels et al. which the Examiner relied upon to allegedly teach the step of "forming an insulating film on the substrate to cover the conductor film" is directed to the first embodiment. Thus, the Examiner has improperly relied upon the first and third embodiments of Brebels et al. to allegedly teach features recited in Applicants' claim 1 because he has failed to provide any motivation for combining the first and third embodiments of Brebels et al.

Second, lines 25 and 26 of column 19 of Brebels et al. state that "multiple layers

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of low dielectric material are built up on the substrate ..." (emphasis added). However, Applicants' claim 1 recites the feature that the insulating film covers the conductor film. Thus, the multiple layers of low dielectric material taught in lines 25 and 26 of column 19 of Brebels et al. cannot be considered to teach or suggest the step of "repeating the insulating film forming step and the insulating film patterning step more than once" as recited in Applicants' claim 1 because the insulating film forming step recited therein requires that the insulating film covers the conductor film. That is, contrary to the Examiner's allegation, lines 22-44 of column 19 of Brebels et al. fails to teach or suggest the feature of "repeating the insulating film forming step and the insulating film patterning step more than once" as recited in Applicants' claim 1.

Third, lines 20-35 of column 8 of Brebles et al. relied upon by the Examiner to allegedly teach the step of "forming an insulating film on the substrate to cover the conductor film" and the rest of Brebels et al. directed to the first embodiment neither teaches nor suggests that this step could or should be repeated.

Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of claim 1 under 35 U.S.C. § 103(a) as being unpatentable over Brebels et al. in view of Kornrumpf et al., further in view of Carey et al., further in view of Ohya et al., and further in view of at least one of: Trinh et al., Peterson, and/or Kroger.

The Examiner has relied upon Kornrumpf et al., Carey et al., Ohya et al., Trinh et al., Peterson, and Kroger to allegedly cure various deficiencies in Brebels et al. However, none of Kornrumpf et al., Carey et al., Ohya et al., Trinh et al., Peterson, and Kroger teach or suggest the steps of "forming an insulating film on the substrate to cover the conductor film" and "repeating the insulating film forming step and the insulating film patterning step more than once" as recited in Applicants' claim 1.

Accordingly, Applicants respectfully submit that Brebels et al., Kornrumpf et al., Carey et al., Ohya et al., Trinh et al., Peterson, and Kroger, applied alone or in combination, fail to teach or suggest the unique combination and arrangement of elements recited in claim 1 of the present application. Claims 2 and 3 depend upon

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claim 1 and are therefore allowable for at least the reasons that claim 1 is allowable.

In view of the foregoing amendments and remarks, Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt allowance are solicited.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

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